2SB1607

Silicon PNP epitaxial planar type

For power switching Complementary to 2SD2469

Features

- ullet Low collector to emitter saturation voltage $V_{CE(sat)}$
- Satisfactory linearity of foward current transfer ratio h_{FE}
- Large collector current I_C
- Full-pack package with outstanding insulation, which can be installed to the heat sink with one screw

Absolute Maximum Ratings $(T_C=25^{\circ}C)$

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	-130	V
Collector to emitter voltage	V _{CEO}	-80	V
Emitter to base voltage	V _{EBO}	-7	V
Peak collector current	I _{CP}	-15	A
Collector current	I_{C}	-7	A
Collector power T _C =25°C	D	40	777
dissipation Ta=25°C	$P_{\rm C}$	2	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Unit: mm 4.6±0.2 2.9±0.2 2.9±0.2 2.0±0.1 2.6±0.1 2.6±0.1 2.5±0.1 2.5±0.1 2.5±0.1 2.5±0.1 2.5±0.1 3.Emitter TO–220E Full Pack Package

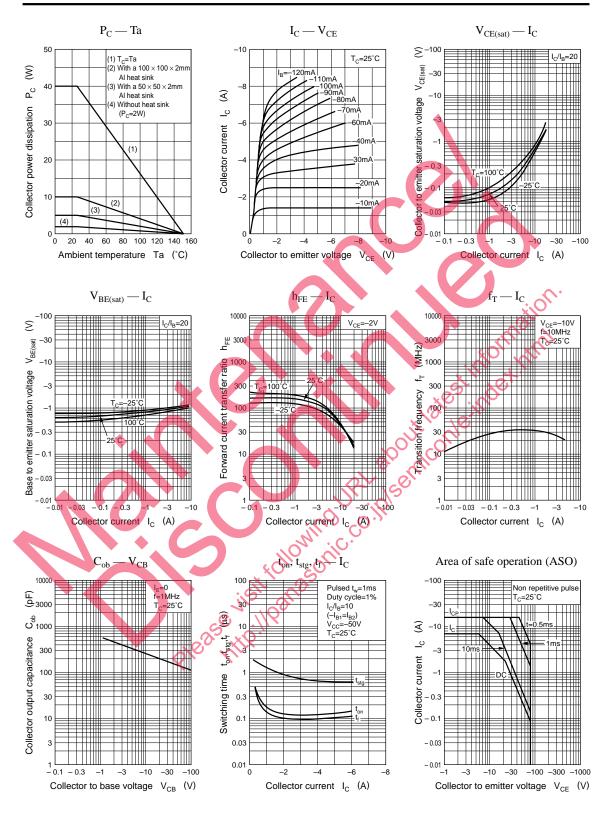
Electrical Characteristics (T_C=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -100V, I_{E} = 0$		71	-10	μА
Emitter cutoff current	I_{EBO}	$V_{EB} = -5V I_C = 0$			-50	μА
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -10$ mA, $I_{\rm B} = 0$	-80			V
Forward current transfer ratio	h _{FE1}	$V_{CE} = -2V, I_{C} = -0.1A$	45			
	h _{FE} 2	$V_{CE} = -2V, I_C = -3A$	90		260	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -5A, I_B = -0.25A$			- 0.5	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = -5A, I_B = -0.25A$			-1.5	V
Transition frequency	f_{T}	$V_{CE} = -10V$, $I_{C} = -0.5A$, $f = 10MHz$		30		MHz
Turn-on time	t _{on}			0.5		μs
Storage time	t _{stg}	$I_C = -3A$, $I_{B1} = -0.3A$, $I_{B2} = 0.3A$		1.5		μs
Fall time	$t_{\rm f}$			0.1		μs

*h_{FE2} Rank classification

Rank	Q	P
h _{FE2}	90 to 180	130 to 260

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